

Short circuit withstand time – 10 μ s

Designed for :

- Frequency Converters
- Uninterrupted Power Supply

Generation for 1200 V applications offers :

- very tight parameter distribution
- high ruggedness, temperature stable behavior

Easy paralleling capability due to positive temperature coefficient in $V_{CE(sat)}$

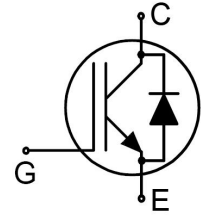
Low EMI

Low Gate Charge

Very soft, fast recovery anti-parallel EmCon HE diode

Qualified according to JEDEC¹ for target applications

Pb-free lead plating; RoHS compliant



Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	1200	V
DC collector current ($T_J=150^\circ\text{C}$)	I_C		A
$T_C = 25^\circ\text{C}$		65	
$T_C = 110^\circ\text{C}$		35	
Pulsed collector current, t_p limited by T_{jmax}	I_{Cpuls}	100	
Turn off safe operating area	-	100	
$V_{CE} \leq 1200\text{V}$, $T_j \leq 175^\circ\text{C}$			
Diode forward current ($T_J=150^\circ\text{C}$)	I_F		
$T_C = 25^\circ\text{C}$		60	
$T_C = 110^\circ\text{C}$		35	
Diode pulsed current, t_p limited by T_{jmax}	I_{Fpuls}	100	
Gate-emitter voltage	V_{GE}	± 20	V
Short circuit withstand time ²⁾	t_{SC}	10	μs
$V_{GE} = 15\text{V}$, $V_{CC} \leq 600\text{V}$, $T_{j, start} \leq 175^\circ\text{C}$			
Power dissipation	P_{tot}	360	W
$T_C = 25^\circ\text{C}$			
Operating junction temperature	T_j	-40...+175	$^\circ\text{C}$
Storage temperature	T_{stg}	-55...+150	
Soldering temperature, 1.6mm (0.063 in.) from case for 10s	-	260	
Wavesoldering only, temperature on leads only			

¹⁾ J-STD-020 and JESD-022

²⁾ Allowed number of short circuits: <1000; time between short circuits: >1s.

Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction – case	R_{thJC}		0.43	K/W
Diode thermal resistance, junction – case	R_{thJCD}		0.81	
Thermal resistance, junction – ambient	R_{thJA}		40	

Electrical Characteristic, at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0V, I_C = 500\mu A$	1200	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C = 35A$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$ $T_j = 175^\circ\text{C}$	- - -	1.97 2.12 2.25	2.1 - -	
Diode forward voltage	V_F	$V_{GE} = 0V, I_F = 35A$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$ $T_j = 175^\circ\text{C}$	- - -	1.88 2.01 2.21	2.1 - -	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 1.0mA, V_{CE} = V_{GE}$	5.2	5.9	6.5	
Zero gate voltage collector current	I_{CES}	$V_{CE} = 1200V,$ $V_{GE} = 0V$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$ $T_j = 175^\circ\text{C}$	- - -	- - -	0.5 4.1 21	mA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0V, V_{GE} = 20V$	-	-	200	
Transconductance	g_{fs}	$V_{CE} = 20V, I_C = 35A$	-	19.5	-	S

Dynamic Characteristic

Input capacitance	C_{iss}	$V_{CE}=25V,$	-	1600	-	pF
Output capacitance	C_{oss}	$V_{GE}=0V,$	-	155	-	
Reverse transfer capacitance	C_{rss}	$f=1MHz$	-	90	-	
Gate charge	Q_{Gate}	$V_{CC}=960V, I_C=40A$ $V_{GE}=15V$	-	120	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E		-	13	-	nH
Short circuit collector current ¹⁾	$I_{C(SC)}$	$V_{GE}=15V, t_{SC} \leq 10\mu s$ $V_{CC}=600V,$ $T_{j,start} = 25^\circ C$ $T_{j,start} = 175^\circ C$	-	150 115	-	A

Switching Characteristic, Inductive Load, at $T_j=25^\circ C$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	

IGBT Characteristic

Turn-on delay time	$t_{d(on)}$	$T_j=25^\circ C,$	-	27	-	ns
Rise time	t_r	$V_{CC}=600V, I_C=35A,$	-	20	-	
Turn-off delay time	$t_{d(off)}$	$V_{GE}=0/15V,$	-	265	-	
Fall time	t_f	$R_G=16.4\Omega,$	-	95	-	
Turn-on energy	E_{on}	$L_\sigma^{2)}=105nH,$	-	1.55	-	mJ
Turn-off energy	E_{off}	$C_\sigma^{2)}=39pF$	-	1.35	-	
Total switching energy	E_{ts}	Energy losses include "tail" and diode reverse recovery.	-	2.9	-	

Anti-Parallel Diode Characteristic

Diode reverse recovery time	t_{rr}	$T_j=25^\circ C,$	-	195	-	ns
Diode reverse recovery charge	Q_{rr}	$V_R=600V, I_F=35A,$	-	2.05	-	μC
Diode peak reverse recovery current	I_{rrm}	$di_F/dt=1050A/\mu s$	-	20	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	475	-	$A/\mu s$

¹⁾ Allowed number of short circuits: <1000; time between short circuits: >1s.

²⁾ Leakage inductance L_σ and Stray capacity C_σ due to dynamic test circuit in Figure E.

Switching Characteristic, Inductive Load, at $T_j=175^\circ\text{C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic						
Turn-on delay time	$t_{d(on)}$	$T_j=175^\circ\text{C}$ $V_{CC}=600\text{V}, I_C=35\text{A},$ $V_{GE}=0/15\text{V},$ $R_G=16.4\Omega,$ $L_{\sigma}^{1)}=175\text{nH},$ $C_{\sigma}^{1)}=67\text{pF}$	-	25	-	ns
Rise time	t_r		-	24	-	
Turn-off delay time	$t_{d(off)}$		-	340	-	
Fall time	t_f		-	164	-	mJ
Turn-on energy	E_{on}	Energy losses include	-	2.25	-	
Turn-off energy	E_{off}	"tail" and diode	-	2.05	-	
Total switching energy	E_{ts}	reverse recovery.	-	4.3	-	
Anti-Parallel Diode Characteristic						
Diode reverse recovery time	t_{rr}	$T_j=175^\circ\text{C}$ $V_R=600\text{V}, I_F=35\text{A},$ $di_F/dt=1000\text{A}/\mu\text{s}$	-	290	-	ns
Diode reverse recovery charge	Q_{rr}		-	3.65	-	μC
Diode peak reverse recovery current	I_{rrm}		-	24	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	330		$\text{A}/\mu\text{s}$

¹⁾ Leakage inductance L_{σ} and Stray capacity C_{σ} due to dynamic test circuit in Figure E.

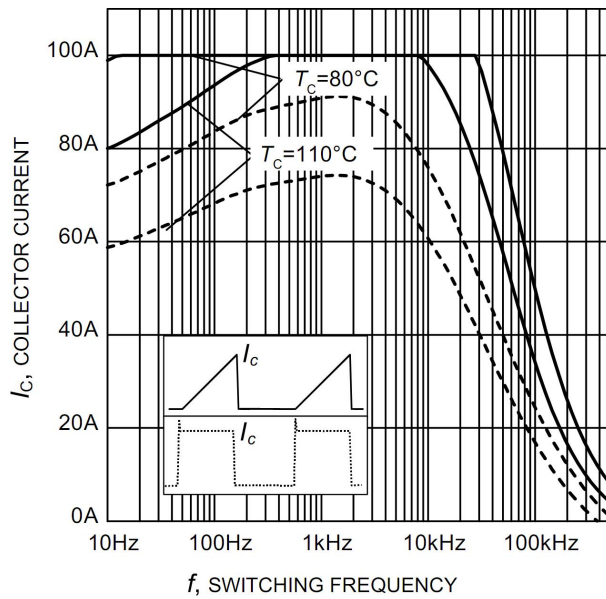


Figure 1. Collector current as a function of switching frequency
 ($T_j \leq 175^\circ\text{C}$, $D = 0.5$, $V_{CE} = 600\text{V}$,
 $V_{GE} = 0/+15\text{V}$, $R_G = 12\Omega$)

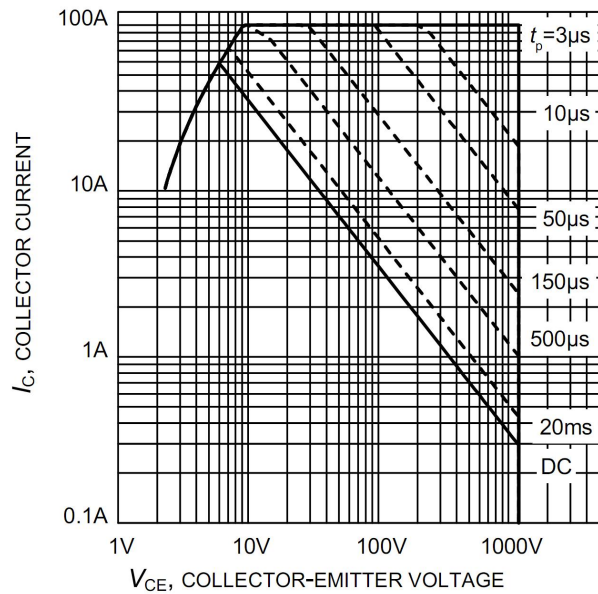


Figure 2. Safe operating area
 ($D = 0$, $T_C = 25^\circ\text{C}$,
 $T_j \leq 175^\circ\text{C}$; $V_{GE} = 15\text{V}$)

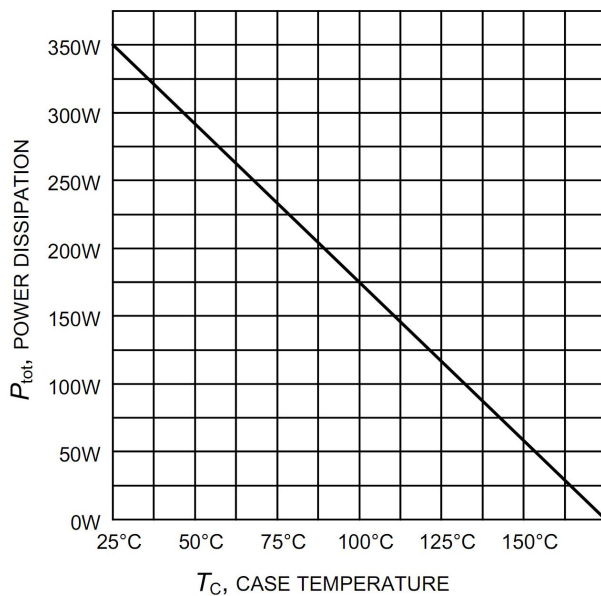


Figure 3. Maximum power dissipation as a function of case temperature
 ($T_j \leq 175^\circ\text{C}$)

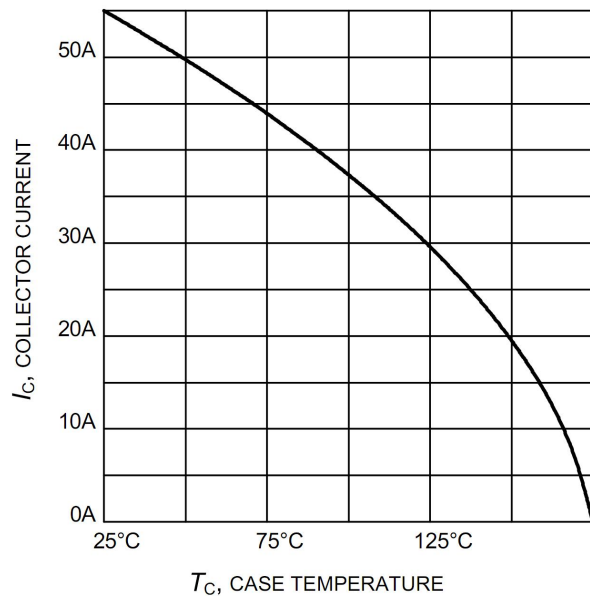


Figure 4. Maximum collector current as a function of case temperature
 ($V_{GE} \geq 15\text{V}$, $T_j \leq 175^\circ\text{C}$)

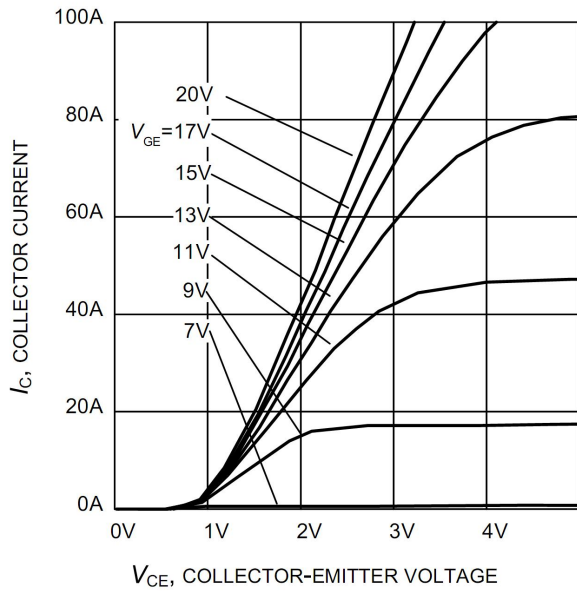


Figure 5. Typical output characteristic
($T_j = 25^\circ\text{C}$)

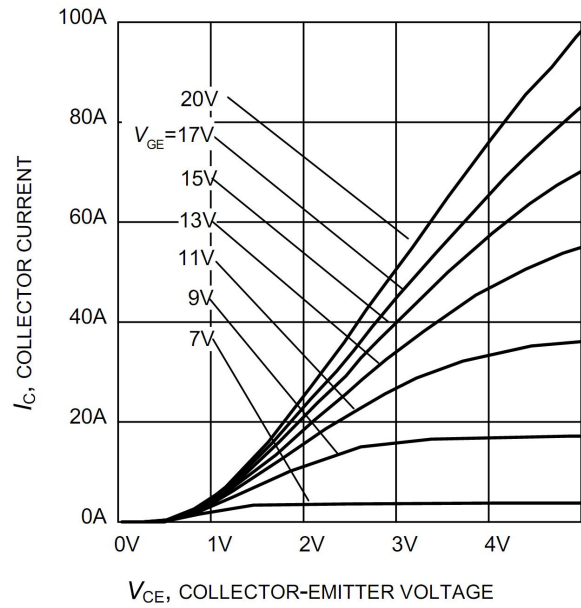


Figure 6. Typical output characteristic
($T_j = 175^\circ\text{C}$)

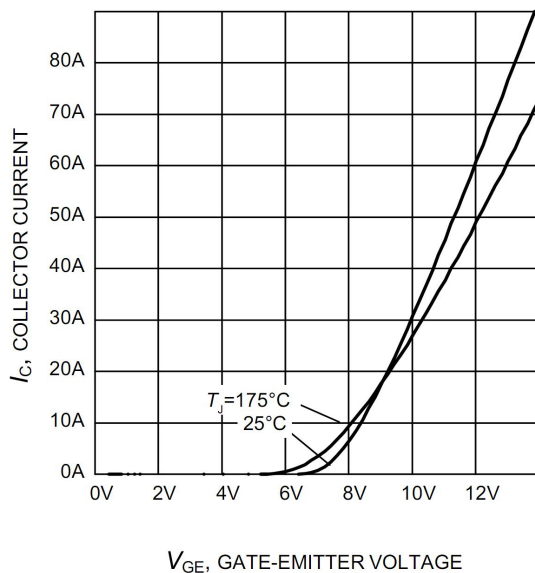


Figure 7. Typical transfer characteristic
($V_{CE} = 20\text{V}$)

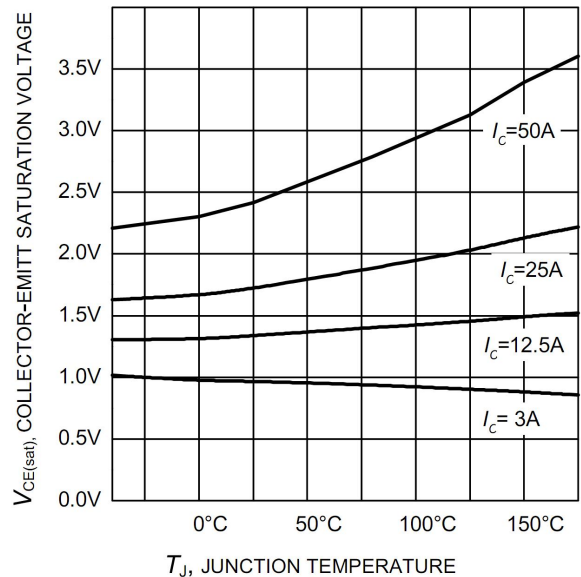


Figure 8. Typical collector-emitter saturation voltage as a function of junction temperature
($V_{GE} = 15\text{V}$)

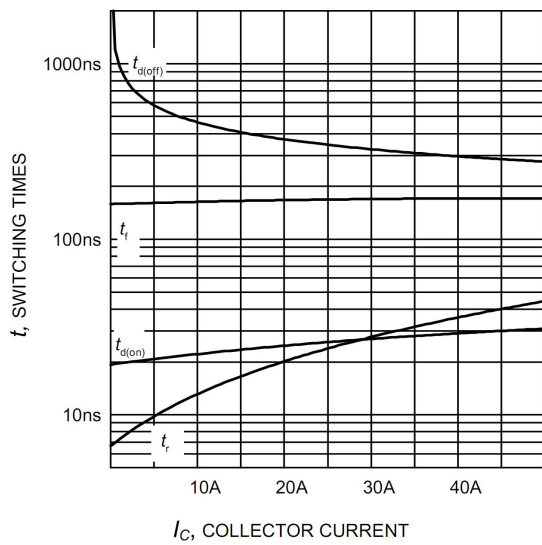


Figure 9. Typical switching times as a function of collector current
 (inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $R_G=16.4\Omega$, Dynamic test circuit in Figure E)

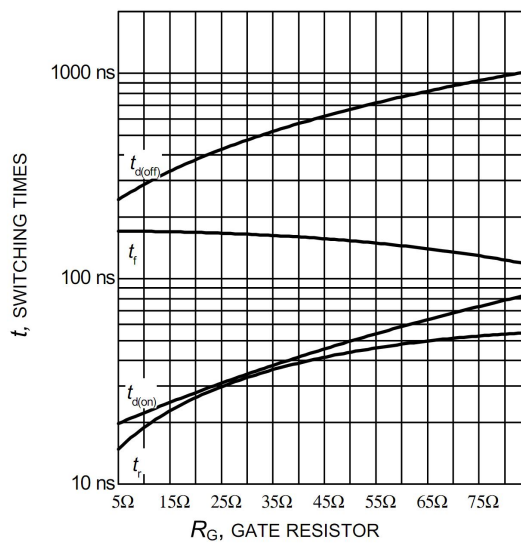


Figure 10. Typical switching times as a function of gate resistor
 (inductive load, $T_J=175^\circ\text{C}$, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=25\text{A}$, Dynamic test circuit in Figure E)

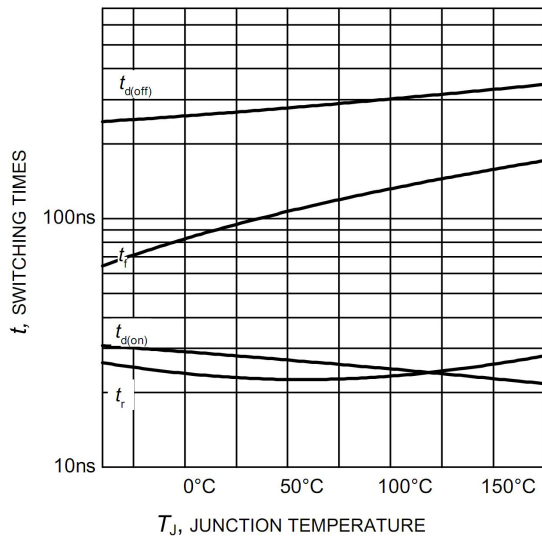


Figure 11. Typical switching times as a function of junction temperature
 (inductive load, $V_{CE}=600\text{V}$, $V_{GE}=0/15\text{V}$, $I_C=25\text{A}$, $R_G=16.4\Omega$, Dynamic test circuit in Figure E)

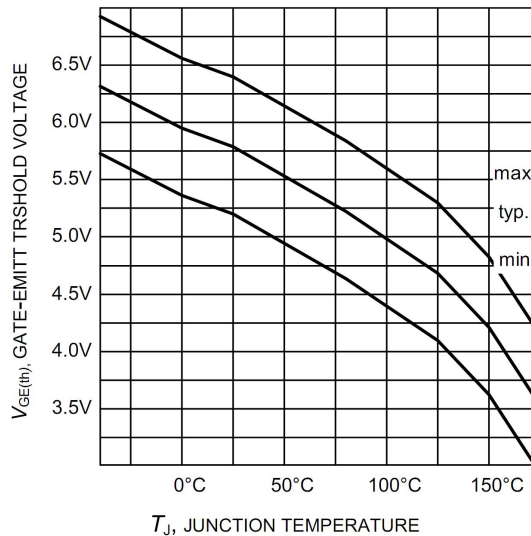
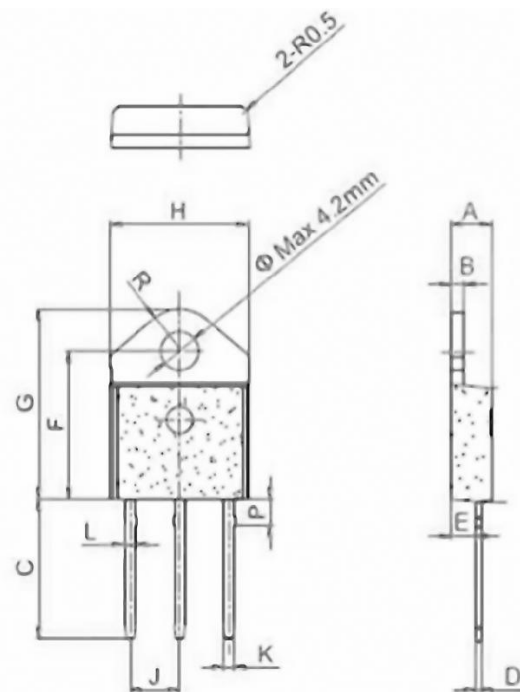


Figure 12. Gate-emitter threshold voltage as a function of junction temperature
 ($I_C = 1.0\text{mA}$)

K35A120DS

SETMEKRON

Package: TO-3P



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.173		0.181
B	1.45		1.55	0.057		0.061
C	14.35		15.60	0.565		0.614
D	0.50		0.70	0.020		0.028
E	2.70		2.90	0.106		0.114
F	15.80		16.50	0.622		0.650
G	20.40		21.10	0.803		0.831
H	15.10		15.50	0.594		0.610
J	5.40		5.65	0.213		0.222
K	1.10		1.40	0.043		0.055
L	1.35		1.50	0.053		0.059
P	2.80		3.00	0.110		0.118
R		4.35			0.171	